

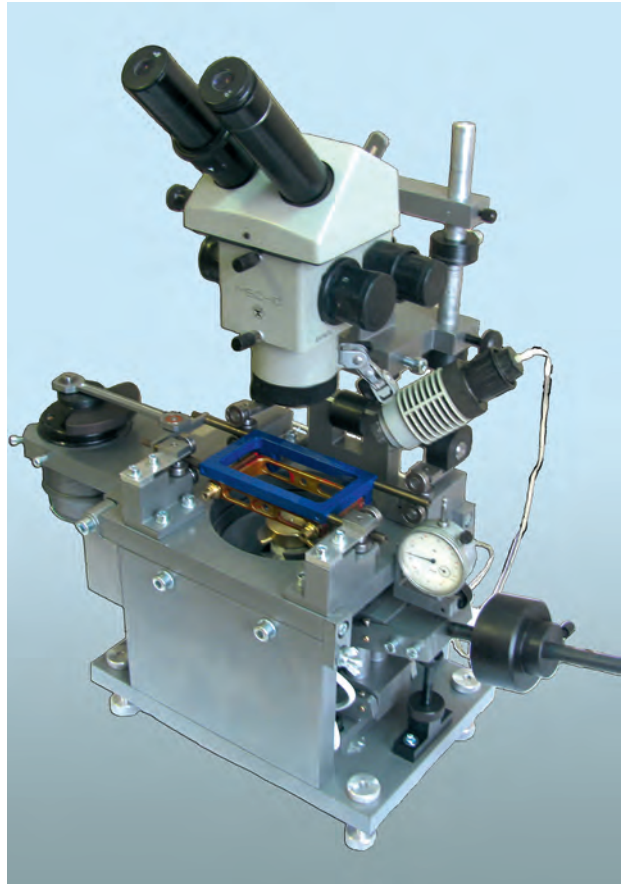
ALTEC-13009 COMPACT MACHINE TOOL FOR CUTTING SEMICONDUCTOR MATERIALS

Areas of Application

The tool is designed for cutting semiconductor materials, glass, quartz, graphite, lead, tin, and other materials into square and rectangular blanks

Specification

Maximum dimensions of work piece to be cut, mm	40 × 40 × 15
Minimum number of strings on the frame.	1
Maximum number of strings on the frame	95
Width of diamond-coated cut, mm	0.22
Width of loose abrasive cut, mm	0.15
Weight, kg	≤12
Power consumption, W	15
Power supply	24 DC
Dimensions, mm	340 × 690 × 630



Advantages

Cutting accuracy with the use of diamond-coated strings, mm	±0.02
Cutting accuracy with the use of loose abrasive strings, mm	±0.01
Cutting depth control accuracy, mm	±0.01

Stage of Development. Suggestions for Commercialization

IRL7, TRL6
Manufacture, supply, warranty service,
and staff training, upon request

IPR Protection

IPR3

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